

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT7507647

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
GIGADEVICE SEMICONDUCTOR (BEIJING) INC.	08/16/2022
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MAGVISION SEMICONDUCTOR (BEIJING) INC.
<b>Street Address:</b>	BUILDING NO. 6, NO.10 KEGU ONE STREET
<b>Internal Address:</b>	ECONOMIC-TECHNOLOGICAL DEVELOPMENT AREA
<b>City:</b>	BEIJING
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	100176
<b>PROPERTY NUMBERS Total: 5</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	63226509
Application Number:	17459039
Application Number:	17478556
Application Number:	17476989
Application Number:	17506947
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	2146515000
<b>Email:</b>	IPDOCKETING@HAYNESBOONE.COM
<b>Correspondent Name:</b>	HAYNES AND BOONE, LLP
<b>Address Line 1:</b>	2323 VICTORY AVENUE, SUITE 700
<b>Address Line 2:</b>	IP SECTION
<b>Address Line 4:</b>	DALLAS, TEXAS 75219
<b>ATTORNEY DOCKET NUMBER:</b>	61696.2 / 62506.2
<b>NAME OF SUBMITTER:</b>	YILUN WANG
<b>SIGNATURE:</b>	/YILUN WANG/
<b>DATE SIGNED:</b>	08/26/2022

**Total Attachments: 3**

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**ASSIGNMENT**

WHEREAS, **GIGADEVICE SEMICONDUCTOR (BEIJING) INC.**, ("ASSIGNOR") a corporation, with offices located at Building No. 8, IC Park, No. 9 Fenghao East Road, Haidian, Beijing, China 100088, is the owner of certain inventions as embodied in and represented by the Intellectual Property, as defined below.

"Intellectual Property" shall collectively mean the technology developed by ASSIGNOR listed in **ATTACHMENT A**, as well as any application related thereto, including, without limitation, for which an application for a Patent of the United States was filed.

WHEREAS, ASSIGNOR is desirous of assigning all of its right in the Intellectual Property to **MAGVISION SEMICONDUCTOR (BEIJING) INC.** ("ASSIGNEE"), a corporation, with offices located at Building No. 6, No.10 Kegou One Street, Economic-Technological Development Area, Beijing, China 100176.

NOW, THEREFORE, subject to the terms, conditions, covenants and provisions of this Assignment, and for other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged by ASSIGNOR, the parties hereto, intending legally to be bound, agree as follows:

ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE, its successors and assigns, said ASSIGNOR'S entire right, title, and interest in the Intellectual Property, including, without limitation, (i) all United States and foreign rights therein, whether patentable or not, and in and to aforesaid patents, patent applications and any divisions or continuations thereof, and any patents or similar registrations obtained for the Intellectual Property in the United States and foreign countries, or issuing out of said application or any such division or continuation thereof, and any reissues or extensions of any such patents, as well as all rights to claim priority to any of the foregoing and (ii) all causes of action, past, present, and future, for infringement, unfair competition or otherwise with respect to the Intellectual Property and all disclosures of ideas, whether or not patentable and all pending applications.

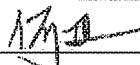
ASSIGNOR hereby authorizes and requests the Commissioner of Patents of the United States, and any official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

ASSIGNOR hereby acknowledges that the entire beneficial interest in the Intellectual Property and to which the above application relates is irrevocably vested in the ASSIGNEE including the right to make the application for protection in all countries abroad and to claim priority under the International Convention for such applications and hereby assents to the making of any such applications, with or without priority claims, and of any divisional application resulting therefrom.

ASSIGNOR further covenants that it will at all times communicate to the ASSIGNEE, its successors, assigns or legal representatives, all facts relating to the Intellectual Property, or the history thereof, known to him, and testify as the same in interferences or other litigation, when requested so to do.

**GIGADEVICE SEMICONDUCTOR (BEIJING) INC.**

Executed and delivered this 16 day of 8 2022.

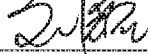
Signature: 

Printed Name: Wei HE

Title: General Manager

**MAGVISION SEMICONDUCTOR (BEIJING) INC.**

Executed and delivered this 25 day of 7 2022.

Signature: 

Printed Name: Lei LIU

Title: CEO

Docket No. 61696.2  
Assignment

INTELLECTUAL PROPERTY  
ATTACHMENT A

Entitled	Country	Serial Number	Filing Date
Image Sensor Pixel With Deep Trench Isolation Structure	US	63/226,509	7/28/2021
Image Sensor Pixel With Deep Trench Isolation Structure	US	17/459,039	8/27/2021
Deep Trench Isolation Structure For Image Sensor	US	17/478,556	9/17/2021
Image Sensor Pixel With Deep Trench Isolation Structure	US	17/476,989	9/16/2021
Image Sensor Pixel With Deep Trench Isolation Structure	US	17/506,947	10/21/2021